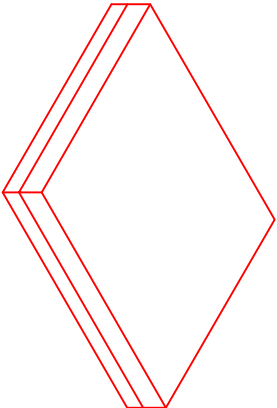


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REV.	DESCRIPTION	DATE	CHECKED	ORIGINATED BY
00	INITIAL RELEASE PER DCN C06108	06/06/99	E.B.	MCN



7. REFERENCE SPECIFICATIONS:
A. AAWT SPEC #001-0631-2234: PACKING OPERATION PROCEDURE.
B. AAWT SPEC #001-0619-2068: MARKING.

6. PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BUMPS IS 84.

3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 12 X 12.

2. THE BASIC SOLDER BUMP GRID PITCH IS 0.50.

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS		PRODUCTION		DRAWING		DATE		TITLE		PACKAGE OUTLINE - CTBGA 84, 7.00mm, X 7.00mm, 2 LAYER, 0.50mm PITCH, LAMINATE SUBSTRATE, AAP	
DECIMAL		ANGULAR		±1°							
XX ±0.10											
XXX ±0.06											
XXXX ±0.03											
TYPICAL											
N/A											
		APPROVALS		DATE							
		H. NOBLES		04/19/99							
		J. WUNDERCH		04/26/99							
		H. BURKHOLDER		04/30/99							
		G. SCHULTZ		05/04/99							
DO NOT SCALE DRAWING											